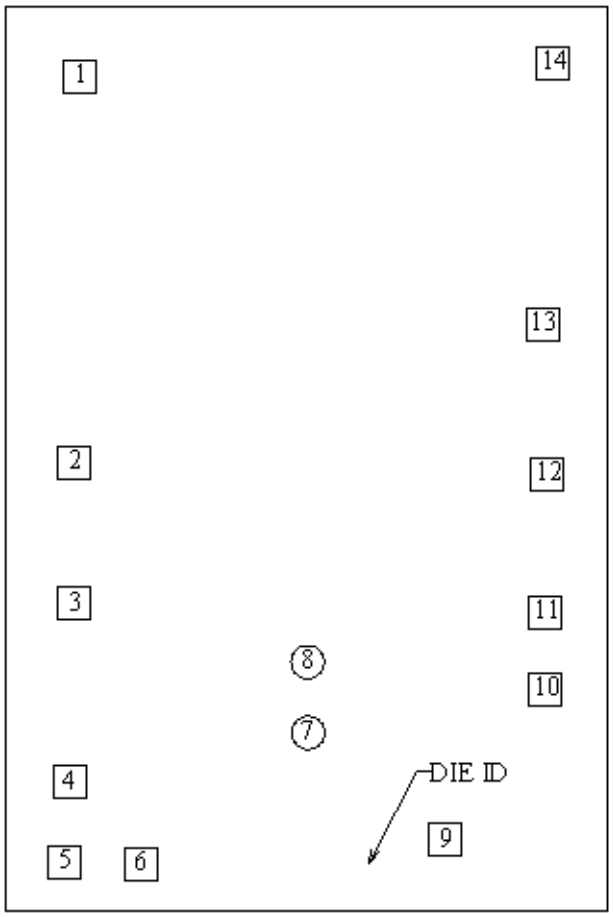
LP2953 MDS
ADJUSTABLE MICROPOWER LOW-DROPOUT VOLTAGE REGULATOR

November 06,2007

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LP2952B	Bond Pad Opening Size (min)	90µm x 90µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1651µm x 2489µm 65.0mils x 98.0mils	Back Side Connection	GND
Thickness	305µm Nominal		
Min Pitch	209µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
OUTPUT	1	-623	1055	90	x	90
SENSE	2	-640	-10	90	x	90
SHUTDOWN	3	-640	-399	90	x	90
ERROR	4	-653	-890	90	x	90
NC	5	-666	-1110	90	x	90
GND	6	-456	-1115	90	x	90
NC	7	4	-753	91	x	90
NC	8	4	-560	91	x	91
COMP OUT	9	382	-1049	90	x	90
COMP INPUT	10	658	-633	90	x	90
REFERENCE	11	658	-424	90	x	90
VTAP	12	663	-43	90	x	90
FEEDBACK	13	649	372	90	x	90
INPUT	14	678	1089	90	x	90

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Notes

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